

Title (en)
COMPOSITIONS AND METHODS FOR DRYING PATTERNED WAFERS DURING MANUFACTURE OF INTEGRATED CIRCUITRY PRODUCTS

Title (de)
ZUSAMMENSETZUNGEN UND VERFAHREN ZUM TROCKNEN VON STRUKTURIERTEN WAFERN BEI DER HERSTELLUNG VON
INTEGRIERTEN SCHALTUNGSPRODUKTEN

Title (fr)
COMPOSITIONS ET PROCÉDÉS POUR SÉCHER DES TRANCHES IMPRIMÉES PAR SÉCHAGE DURANT LA FABRICATION DE CIRCUITS
IMPRIMÉS

Publication
EP 1765526 A1 20070328 (EN)

Application
EP 04751653 A 20040507

Priority
US 2004014353 W 20040507

Abstract (en)
[origin: WO2005113167A1] Drying of patterned wafers is achieved in a manner effecting removal of water from the patterned wafers without collapse or deterioration of the pattern structures thereof. The drying is carried out in one aspect of the invention with a composition containing supercritical fluid, and at least one water-reactive agent that chemically reacts with water to form reaction product(s) more soluble in the supercritical fluid than water. Various methodologies are described for use of supercritical fluids to dry patterned wafers, which avoid the (low water solubility) deficiency of supercritical fluids such as supercritical CO₂.

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